



Micro/Nano Devices and Its Tribology

Guest Editor:

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Message from the Guest Editor

Summary

With the development of more sophisticated manufacturing process (e.g., EUV, extreme ultraviolet), the minimum dimensions of electronic device components have reached down to several nm in order to maximize the level of integration and enhance the performance within a limited volume. This Special Issue seeks to showcase research papers, short communications, and review articles that focus on the tribology of microelectronic devices, soft electronics, MEMS, and other microelectronic devices for tribological applications. Of interest are also papers that examine the tribological properties (i.e., friction, wear, surface engineering, and durability, to name a few) of novel materials for microelectronic devices.

We look forward to receiving your submissions!

Prof. Dr. Hae-Jin Kim

Guest Editor

Keywords:

tribology of microelectronic devices; tribology of soft electronics; tribology of MEMS; microelectronic devices for tribological applications; tribological properties of the materials for microelectronic devices





Editor-in-Chief

Message from the Editor-in-Chief

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